Product data sheet

1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a leadless medium power DFN2020MD-6 (SOT1220) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- · Logic-level compatible
- Extended temperature range T_i = 175 °C
- Side wettable flanks for optical solder inspection
- Small and leadless ultra thin SMD plastic package: 2 x 2 x 0.65 mm
- Trench MOSFET technology
- AEC-Q101 qualified

3. Applications

- Relay driver
- High-speed line driver
- · High-side load switch
- · Switching circuits

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{DS}	drain-source voltage	T _j = 25 °C	-	-	-60	V
V_{GS}	gate-source voltage		-20	-	20	V
I _D	drain current	V _{GS} = -10 V; T _{sp} = 25 °C	-	-	-8	Α
P _{tot}	total power dissipation	T _{sp} = 25 °C	-	-	15	W
Static chara	acteristics		•			
R _{DSon}	drain-source on-state resistance	V_{GS} = -10 V; I_D = -3 A; T_j = 25 °C	-	95	120	mΩ



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	D	drain		
2	D	drain		D
3	G	gate		
4	S	source	2 5	_G (↓⊨¬▼)
5	D	drain	3 8 4	
6	D	drain	Transparent top view	S
7	D	drain	DFN2020MD-6 (SOT1220)	017aaa094
8	S	source		

6. Ordering information

Table 3. Ordering information

Type number	Package					
	Name	Description	Version			
BUK9D120-60P		plastic, leadless thermal enhanced ultra thin small outline package with side-wettable flanks (SWF); 6 terminals; 0.65 mm pitch; 2 mm x 2 mm x 0.65 mm body	SOT1220			

7. Marking

Table 4. Marking codes

Type number	Marking code
BUK9D120-60P	RJ

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{DS}	drain-source voltage	T _j = 25 °C		-	-60	V
V _{GS}	gate-source voltage			-20	20	V
I _D	drain current	V _{GS} = -10 V; T _{sp} = 25 °C		-	-8	Α
		V _{GS} = -10 V; T _{sp} = 100 °C		-	-5.1	Α
		V _{GS} = -10 V; T _{amb} = 25 °C	[1]	-	-3	Α
I _{DM}	peak drain current	T_{sp} = 25 °C; single pulse; $t_p \le 10 \mu s$		-	-32	Α
P _{tot}	total power dissipation	T _{sp} = 25 °C		-	15	W
		T _{amb} = 25 °C	[1]	-	2.3	W
Tj	junction temperature			-55	175	°C
T _{amb}	ambient temperature			-55	175	°C
T _{stg}	storage temperature			-65	175	°C
Source-draii	n diode					
Is	source current	T _{sp} = 25 °C		-	-8	Α
		T _{amb} = 25 °C	[1]	-	-2.3	Α
I _{SM}	peak source current	single pulse; t _p ≤ 10 µs; T _{sp} = 25 °C		-	-32	Α
Avalanche r	uggedness					
E _{DS(AL)S}	non-repetitive drain- source avalanche energy	$T_{j(init)}$ = 25 °C; I_D = -1.6 A; DUT in avalanche (unclamped)		-	28	mJ

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².

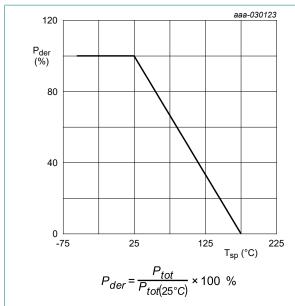


Fig. 1. Normalized total power dissipation as a function of solder point temperature

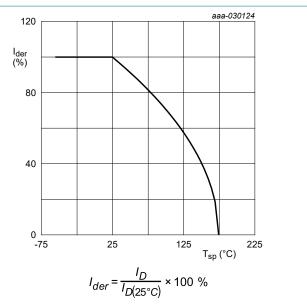


Fig. 2. Normalized continuous drain current as a function of solder point temperature

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60 V, P-channel Trench MOSFET

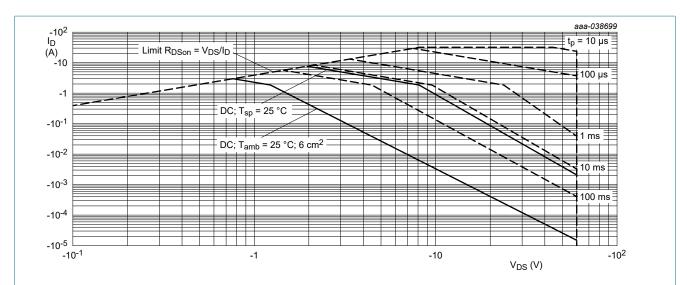


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	57	66	K/W
R _{th(j-sp)}	thermal resistance from junction to solder point			-	6	10	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².

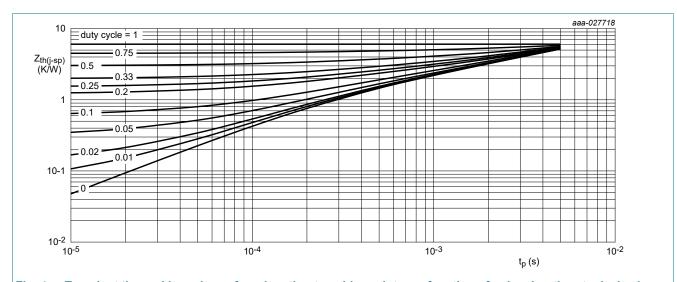


Fig. 4. Transient thermal impedance from junction to solder point as a function of pulse duration; typical values

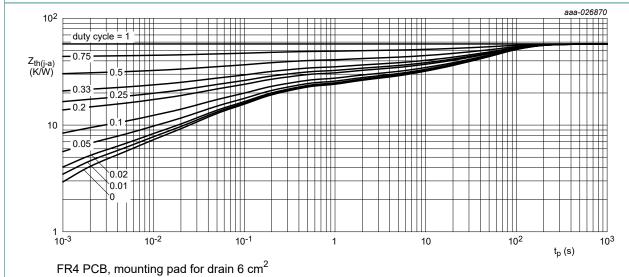


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	acteristics					
V _{(BR)DSS}	drain-source breakdown voltage	$I_D = -250 \ \mu A; \ V_{GS} = 0 \ V; \ T_j = 25 \ ^{\circ}C$	-60	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = -250 \mu A; V_{DS} = V_{GS}; T_j = 25 °C$	-1.5	-2	-2.5	V
I _{DSS}	drain leakage current	V _{DS} = -60 V; V _{GS} = 0 V; T _j = 25 °C	-	-	-1	μΑ
		V _{DS} = -60 V; V _{GS} = 0 V; T _j = 125 °C	-	-	-20	μΑ
I _{GSS}	gate leakage current	$V_{GS} = -20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}$	-	-	-100	nA
		V _{GS} = 20 V; V _{DS} = 0 V; T _j = 25 °C	-	-	100	nA
DOON	drain-source on-state	V_{GS} = -10 V; I_D = -3 A; T_j = 25 °C	-	95	120	mΩ
	resistance	V _{GS} = -10 V; I _D = -3 A; T _j = 175 °C	-	202	256	mΩ
		V _{GS} = -4.5 V; I _D = -2.5 A; T _j = 25 °C	-	112	160	mΩ
9 _{fs}	forward transconductance	V_{DS} = -10 V; I_{D} = -3 A; T_{j} = 25 °C	-	13	-	S
R_G	gate resistance	f = 1 MHz	-	8	-	Ω
Dynamic ch	naracteristics				- 1	
Q _{G(tot)}	total gate charge	V _{DS} = -30 V; I _D = -3 A; V _{GS} = -10 V;	-	12	18	nC
Q _{GS}	gate-source charge	T _j = 25 °C	-	2.1	-	nC
Q_{GD}	gate-drain charge		-	2.4	-	nC
C _{iss}	input capacitance	V _{DS} = -30 V; f = 1 MHz; V _{GS} = 0 V;	-	713	-	pF
C _{oss}	output capacitance	T _j = 25 °C	-	48	-	pF
C _{rss}	reverse transfer capacitance		-	27	-	pF
t _{d(on)}	turn-on delay time	$V_{DS} = -30 \text{ V}; I_D = -3 \text{ A}; V_{GS} = -10 \text{ V};$	-	3	-	ns
t _r	rise time	$R_{G(ext)} = 6 \Omega; T_j = 25 °C$	-	4	-	ns
t _{d(off)}	turn-off delay time		-	24	-	ns
t _f	fall time		-	21	-	ns
Source-drai	in diode		'			
V_{SD}	source-drain voltage	I_S = -2.3 A; V_{GS} = 0 V; T_j = 25 °C	-	-0.9	-1.2	V
t _{rr}	reverse recovery time	$I_S = -2.3 \text{ A}$; $dI_S/dt = 100 \text{ A/µs}$;	-	19	-	ns
Q _r	recovered charge	$V_{GS} = 0 \text{ V}; V_{DS} = -30 \text{ V}; T_j = 25 \text{ °C}$	-	15	-	nC

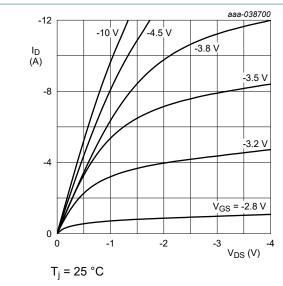


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

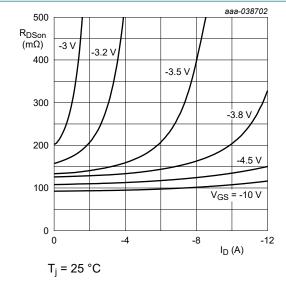


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

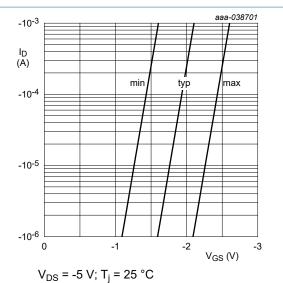


Fig. 7. Sub-threshold drain current as a function of

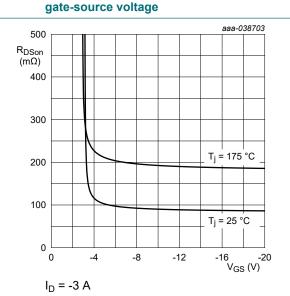


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

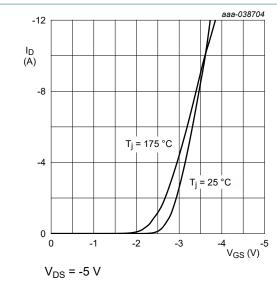


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

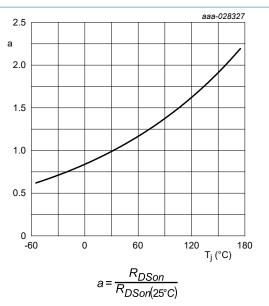


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

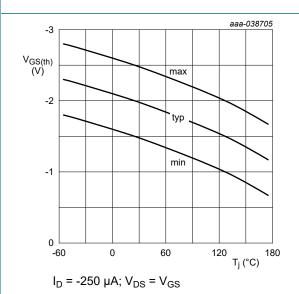
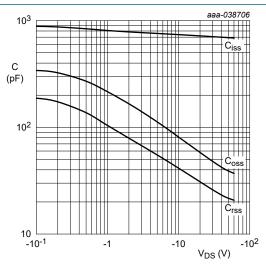


Fig. 12. Gate-source threshold voltage as a function of junction temperature



 $f = 1 MHz; V_{GS} = 0 V$

Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

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60 V, P-channel Trench MOSFET

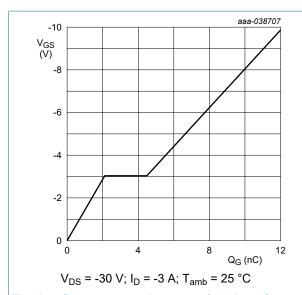


Fig. 14. Gate-source voltage as a function of gate charge; typical values

 $V_{GS} = 0 V$

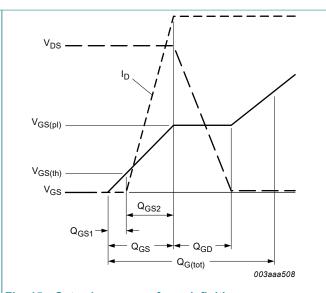


Fig. 15. Gate charge waveform definitions

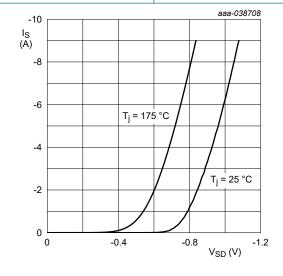
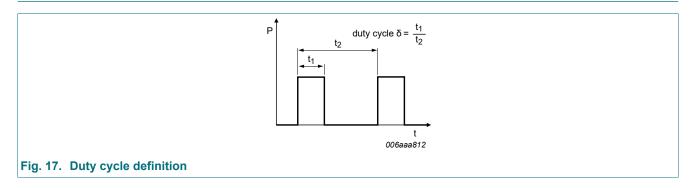


Fig. 16. Source current as a function of source-drain voltage; typical values

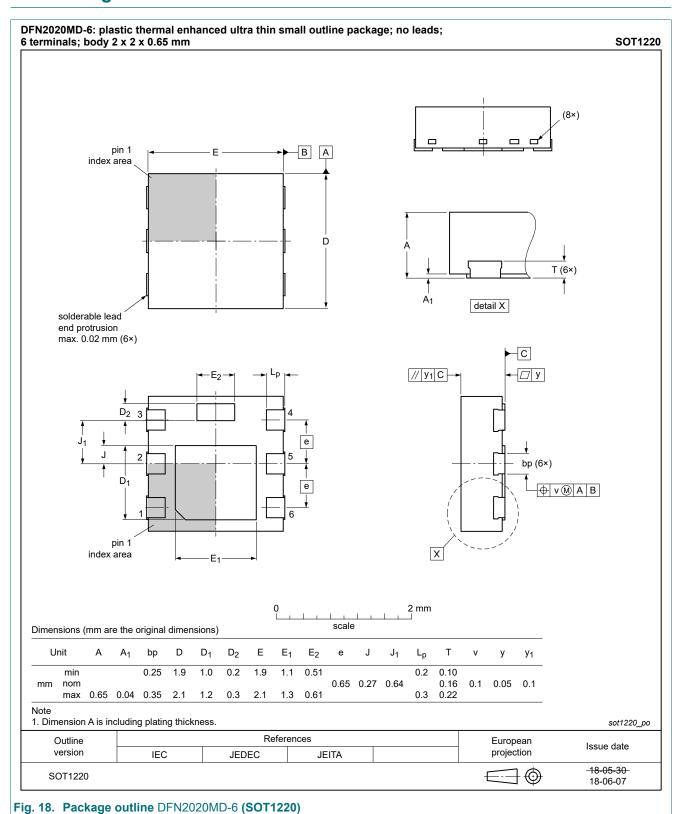
11. Test information



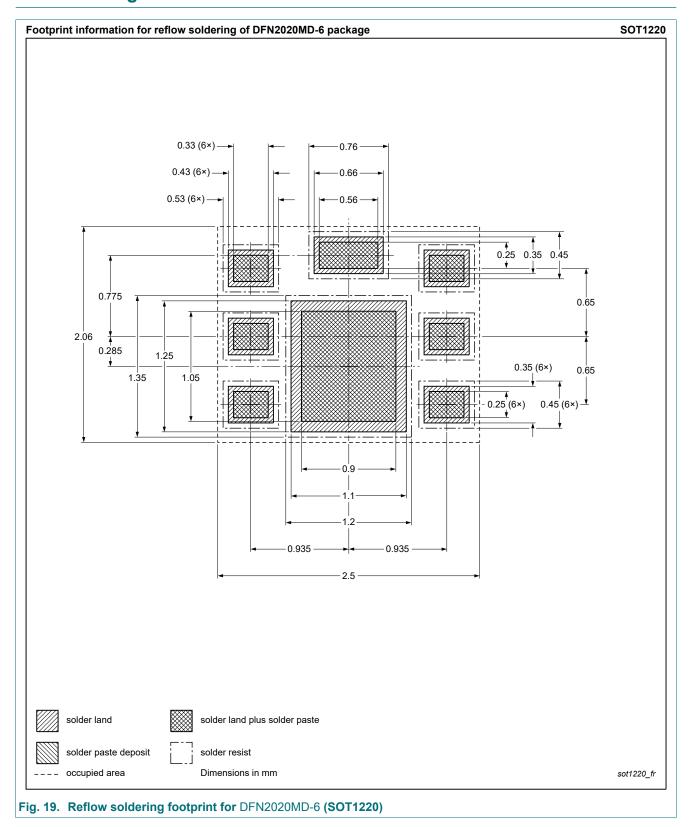
Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline



13. Soldering



14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BUK9D120-60P v.1	20240209	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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Contents

1.	General description	1
2.	Features and benefits	1
3.	Applications	1
4.	Quick reference data	1
5.	Pinning information	2
6.	Ordering information	2
7.	Marking	2
8.	Limiting values	3
9.	Thermal characteristics	5
10.	Characteristics	6
11.	Test information	. 10
12.	Package outline	11
	Soldering	
14.	Revision history	.13
	Legal information	
	-	

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